

---

# **PRODUCT CHANGE NOTICE**

**Data Sheet and Wafer  
Fabrication Site Change for  
Intersil Product ISL59482\***

**Refer to:  
PCN12061**

**Date: July 27, 2012**

July 27, 2012

To: Our Valued Intersil Customer

Subject: **Data Sheet and Wafer Fabrication Site Change for Intersil Product ISL59482\* –**  
*NXP Semiconductor Nijmegen, Netherlands*

This notice is to inform you that Intersil has qualified the NXP Semiconductor facility in Nijmegen, Netherlands for wafer fabrication of the ISL59482\* HS6 technology products. The change in wafer fabrication site is necessary as the NXP facility in Fishkill, New York has discontinued manufacturing operations. The HS6 technology wafer fabrication process has been relocated from the NXP Fishkill to the NXP Nijmegen facility. The data sheet has been updated to align the specification with the characteristics of the product (silicon) fabricated at the NXP Nijmegen facility. The updated data sheet is available on the Intersil web site at <http://www.intersil.com/data/fn/fn6209.pdf>. As of this notice, the data sheet updates and product qualification activities are complete.

Products affected: **ISL59482IRZ ISL59482IRZ-T13 ISL59482IRZ-T13S2490**

The data sheet specification changes are as follows:

**Electrical Specification Table:**

Parameter	Description	Current Limit			New Limit			Units
		Min	Typ	Max	Min	Typ	Max	
+Is Enabled	Enabled Supply Current	77	88	96	77	88	<b>100</b>	mA
+Is Disabled	Disabled Supply Current	4	6.8	7.6	4	6.8	<b>8</b>	

The NXP Nijmegen facility is ISO 9001:2008 and ISO/TS 16949:2002 certified. The product and site qualification plans are designed using JEDEC and other applicable industry standards to confirm form, fit, function, or interchangeability of the product. A summary of the technology qualification results is included for reference. The remainder of the manufacturing operations will continue to be processed to previously established conditions and systems. Product affected by this change is identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product from either the current or the newly qualified sites and screened to the updated data sheet beginning ninety days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,



Jon Brewster  
Intersil Corporation

PCN12061

CC: J. Touvell J. McNamara M. Carmody J. Yun H. Babcock C. Liu L. Tran

## NXP HS6 Technology Qualification Summary – PCN12061

Reliability Test	EL4543 NXP - HS6 Wafer Fabrication Process 24 Lead QSOP	ISL1557 NXP - HS6 Wafer Fabrication Process 16 LEAD 4X4 QFN
High Temperature Operating Life	0/240 125C for 2000 hours	0/80 125C for 2000 hours
	disposition = Passed	disposition = Passed
High Temperature Storage	0/78 150C Bake and Reflow, 1000 hours	N/A
	disposition = Passed	
Unbiased HAST	0/80 130C, 85%RH for 96 hours	0/78 130C, 85%RH for 96 hours
	disposition = Passed	disposition = Passed
Biased HAST	0/158 130C, 85%RH for 96 hours	N/A
	disposition = Passed	
Bond Pull Integrity	0/6 175C for 96hours	0/3 175C for 96hours
	disposition = Passed	disposition = Passed
Temperature Cycle	0/80 -40C to 125C, 1000 cycles	0/78 -40C to 125C, 1000 cycles
	disposition = Passed	disposition = Passed